



Material Composition Declaration

EPC2007

Company Name	Efficient Power Conversion (EPC)	Issue Date:	5/4/2016
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	3.3 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight (mg)	Mass (%)	Sum (%)	Mass (ppm)
Chip	Silicon	7440-21-3	2.9085	87.82	89.80	878156
	Silicon oxide	7631-86-9	0.0110	0.33		3327
	Silicon nitride	12033-89-5	0.0033	0.10		1002
	Gallium nitride	25617-97-4	0.0142	0.43		4297
	Aluminum	7429-90-5	0.0214	0.65		6467
	Aluminum nitride	24304-00-5	0.0033	0.10		997
	Titanium	7440-32-6	0.0005	0.01		144
	Titanium nitride	25583-20-4	0.0027	0.08		800
	Copper	7440-50-8	0.0007	0.02		215
	Tungsten	7440-33-7	0.0006	0.02		169
	Polyimide		0.0080	0.24		2428
Under Bump Metal	Titanium	7440-32-6	0.0005	0.02	0.19	159
	Nickel	7440-02-0	0.0016	0.05		474
	Vanadium	7440-62-2	0.0001	0.00		24
	Copper	7440-50-8	0.0042	0.13		1263
Solder Bump	Tin	7440-31-5	0.3165	9.56	10.01	95575
	Silver	7440-22-4	0.0133	0.40		4003
	Copper	7440-50-8	0.0017	0.05		500
Sum in total:			3.3	100	100	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.